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<u>Irene Hu</u>	<u>Irene Hu</u>
Print Name	Signature

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VIA FACSIMILE: 703-872-9306  
November 8, 2004

MS AMENDMENT  
Commissioner For Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Re: U.S. Utility Patent Application	Group Art Unit:	2839
Appl. No.: <u>10/658,431</u>	Examiner:	Prasad, C.
Filed: <u>09/08/2003</u>	Atty Docket No.:	IAT-P002
Inventor(s): Chang, et al.		

For: "Integrated Multi-Chip Connector Module And Method"

Dear Sir:

The following documents are forwarded herewith for action by the U.S. Patent and Trademark Office:

1. Form PTO-1082;
2. Amendment (12 pages)

Respectfully submitted,

Irene Hu  
Irene Hu  
Reg. No. 34,625

11-8-2004  
Date

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FROM : I. HU

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Print Name: <u>Irene Hu</u>	Signature: <u>[Signature]</u>

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Mail Stop: Amendment  
Commissioner For Patents  
PO Box 1450  
Alexandria, VA 22313-1450

### AMENDMENT TRANSMITTAL LETTER

Sir:

Transmitted herewith for filing relating to U.S. Patent Application of  
Application No.: 10/658,431 Group Art Unit: 2839  
Filed: 09/08/2003 Examiner: Prasad, C.  
Inventor(s): Chang, et al. Atty. Docket No.: IAT-P002

Entitled: "Integrated Multi-Chip Connector Module And Method"

Associated Filing Documents Enclosed:

- ☒ Cover Sheet For Enclosed Documents
- ☒ Amendment: Response Amendment 12 pages total

#### FEES DUE

☒ Applicant Claims Small Entity Status (37 CFR 1.27)

The fees due associated with this correspondence pursuant to 37 C.F.R. 1.16 and for recording the Assignment, if any, are determined as follows:

CLAIMS					
	No. of Claims		Extra Claims	Rate	Fees
Basic Application Fee (\$770 large entity; \$385 small entity)					
Total Pending Claims In Application	11	Minus Basic Allowed 20 =		X \$18 = X \$9 (small) =	\$ 00.00 \$ 00.00
Adjustment: Prior Paid Claims		Minus Prior Paid 20 =		X \$18 = X \$9 (small) =	-\$ 00.00
Total Current Independent Claims	2	Minus Prior Paid 3 =	0	X \$86 = X \$43 (small) =	\$ 00.00
If Multiple Dependent Claims are presented, add \$280.00 or \$100.00 (small)					
If Assignment enclosed, add Assignment Recording Fee \$40.00					
<b>TOTAL APPLICATION FEE DUE</b>					<b>\$ 00.00</b>

#### PAYMENT OF FEES

The full fee due in connection with this communication is \$ 00.00

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and is provided as follows:

- ☐ The Commissioner is hereby authorized to charge the fees associated with this communication or credit any overpayment to Deposit Account No: 502465.
- ☐ A Check No. \_\_\_\_\_ for \$ 00.00 is enclosed. However, the Commissioner is hereby also authorized to charge any additional necessary amount associated with this communication or credit any overpayment to Deposit Account No: 502465.
- ☒ No fee required. However, the Commissioner is hereby ~~is~~ authorized to charge any necessary additional amount associated with this communication or credit any overpayment to Deposit Account No: 502465.

**NO 18 MONTHS PUBLICATION**

**REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b) (1) (B) (i)**

☐ I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen month after filing. I hereby request that the attached application not to be publish under 35 U.S.C. 122(b).

☒ Request previously filed.

Please direct all correspondence concerning the above-identified application to the following address:

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Email: i\_hu@sbcglobal.net

Respectfully submitted,



Irene Hu  
Reg. No. 34,625

Rev. 10/05/2004

11-8-2004  
Date

Irene Hu, Patent Attorney, 2033 Ralston Ave., #146, Belmont, CA 94002  
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<u>IRENE HU</u> Print Name	<u>[Signature]</u> Signature

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In Re Patent Application:

Inventor:	Chang, et al.	Atty Docket No.:	IAT-P002
5 Serial No.:	10/658,431	Group Art Unit:	2839
Filed:	09/08/2003	Examiner:	Prasad, C.
Title:	Integrated Multi-Chip Connector Module And Method		

10 MS Amendment  
Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Amendment/Response To A Non-Final Action Under 37 CFR §1.111

15 Dear Sir:

In response to Official Action of 08/27/2004, please amend the above-identified application as provided herein, the contents being organized as follows:

- Amendment to the Title begins on page 2.
- 20 Amendment to the Claims begins on page 3.
- Remarks/Arguments begins on page 6

Appl. No.: 10/658,431

Docket No: IAT-P002

Filed: 09/08/2003

Response/ Amendment

Amendment to the Title

Please replace the Title of this application with:

A Multi-Chip Connector Module Having One Or More Semiconductor Dice

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a set of input connector pins, each input connector pin further comprising a first end and a second end, wherein the first end is provided to receive an incoming signal, and the second end is electrically connected to the one or more integrated-circuits semiconductor dice on the substrate; and

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a set of output connector pins, each output connector pin further comprising a first and a second end, wherein the first end is electrically connected to the one or more integrated circuits semiconductor dice, and the second end is provided for transmitting a processed signal from the one or more integrated-circuits semiconductor dice as an output signal to the second end of each output connector pin; and

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a connector housing for encasing the array of substrate assemblies, wherein the housing comprises a first set of signal pin apertures through which extend the set of input connector pins to allow external electrical connection to a first external device, and wherein the housing further comprises a second set of signal pin apertures through which extend the set of output connector pins to allow external electrical connection to a second external device, wherein the connector housing further comprises injection-molding a thermally conductive composite around the array of substrate assemblies to fill a plurality of cavities between the array of substrate assemblies, the injection-molded connector housing thereby forming a semiconductor packaging for the one or more semiconductor dice while securing in place the array of substrate assemblies, the one or more semiconductor dice, and the plurality of input and output connector pins.

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2. (Original) The integrated multi-chip connector module of Claim 1 wherein each substrate assembly further comprises a set of pin anchoring means, the set of pin anchoring means anchors the input or output connector pins to the substrate assembly.

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3. (Original) The integrated multi-chip connector module of Claim 1 wherein the second end of each input or output connector pin terminates in an electrically conductive pad.

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